MSKSEMI















ESD

TVS

TSS

MOV

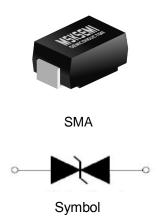
GDT

PLED

Broduct data sheet







Features

Low capatcitance Cannot be damaged by voltage Will not fatigue Eliminate voltage overshoot Glass passivated junction Halogen free and RoHS compliant

Mechanical Data

CASE: SMAJ(DO-214AC) Molded Plastic UL Flammability Classification Rating 94V0 Mounting Position:Any

Maximum Ratings & Thermal Characteristics

(Ratings at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Units	Remarks
Peak Pulse Voltage	V _{PP}	4000	V	10/700us
Peak Pulse Current	IPP	80	Α	10/1000us
Peak Pulse Current	I _{PK}	250	Α	8/20us
Peak One-cycle Surge Current	I _{TSM}	25	Α	60Hz
Rate of Rise of Current	di/dt	500	A/us	
Typical Thermal Resistance Junction to Lead	$R_{ heta JL}$	30	°C/W	
Typical Thermal Resistance Junction to Ambient	R _{eJA}	120	°C/W	
Operating Temperature Range	TJ	-40 to 150	°C	
Storage Temperature Range	T _{STG}	-55 to 150	$^{\circ}$	



Electrical Characteristics

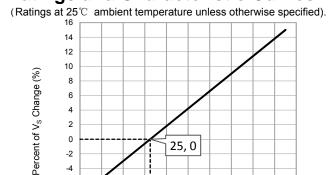
(Ratings at 25 $^{\circ}\mathrm{C}$ ambient temperature unless otherwise specified).

P/N	Mark	V _S @100KV/S V MAX	I _{S_LMT} mA	V _T @ I _T ∨ MAX	I _T	I _D @ V _D uA MAX	V _D	C _O @1MHz,2V _{DC} pF TYP	l _H mA MIN
P0080TB-MS	P008B XXXX	25	500	4	2.2	5	6	29	40
P0220TB-MS	P02B XXXX	30	500	4	2.2	5	15	29	40
P0300TB-MS	P03B XXXX	40	500	4	2.2	5	25	28	40
P0640TB-MS	P06B XXXX	77	800	4	2.2	5	58	27	120
P0720TB-MS	P07B XXXX	88	800	4	2.2	5	65	27	120
P0900TB-MS	P09B XXXX	98	800	4	2.2	5	75	27	120
P1100TB-MS	P11B XXXX	130	800	4	2.2	5	90	25	120
P1300TB-MS	P13B XXXX	160	800	4	2.2	5	120	25	120
P1500TB-MS	P15B XXXX	180	800	4	2.2	5	140	24	120
P1800TB-MS	P18B XXXX	220	800	4	2.2	5	170	22	120
P2300TB-MS	P23B XXXX	260	800	4	2.2	5	190	21	120
P2600TB-MS	P26B XXXX	300	800	4	2.2	5	220	20	120
P3100TB-MS	P31B XXXX	350	800	4	2.2	5	275	18	120
P3500TB-MS	P35B XXXX	400	800	4	2.2	5	320	17	120
P4500TB-MS	P45B XXXX	530	800	4	2.2	5	400	13	120

-6

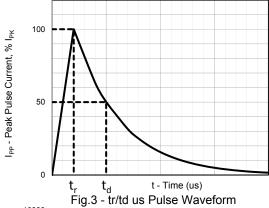
-40

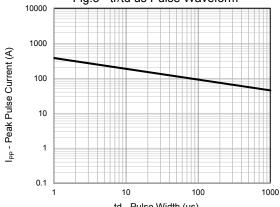
Ratings and Characteristic Curves



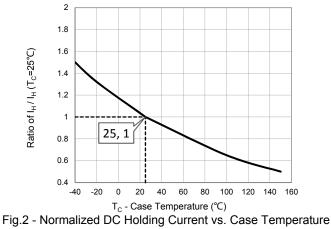
 T_J - Junction Temperature (°C) Fig.1 - Peak Pulse Current Rating

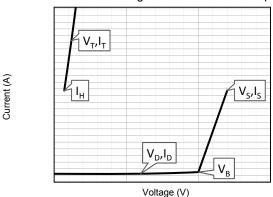
40 60 100 120 140 160

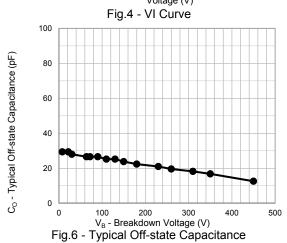




td - Pulse Width (us)
Fig.5 - Peak Pulse Current Rating



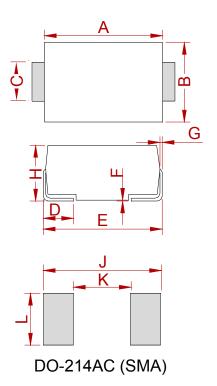




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PACKAGE MECHANICAL DATA



	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
Α	4.25	4.65	0.167	0.183	
В	2.50	2.90	0.098	0.114	
С	1.35	1.65	0.053	0.065	
D	0.76	1.52	0.030	0.060	
E	4.93	5.28	0.194	0.208	
F	0.051	0.203	0.002	0.008	
G	0.15	0.31	0.006	0.012	
Н	1.98	2.41	0.078	0.095	
J	6.50		0.256		
K		2.30		0.090	
L	1.70		0.067		

REEL SPECIFICATION

P/N	PKG	QTY
PXXXXTB-MS	SMA	5000



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